

PUBLICATION LIST

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A. Published Books and Parts of Books

1. Su, B. and Qu, J., 2008, "Fatigue Behavior of Electrically Conductive Adhesives," in Electrically Conductive Adhesives, ed. R. Gomatam and K.L., Mittal, Koninklijke Brill NV., Leiden, The Netherlands, pp. 251 – 270.
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5. Qu, J. and L. Jacobs, 2004, "Cylindrical Waves and Their Applications in Ultrasonic Evaluation," in Ultrasonic NDE for Engineering and Biological Material Characterization, ed. T. Kundu, CRC Press, p.311 – 362.
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B. Refereed Publications

1. Treiber, M., Kim, J.Y., Jacobs, L.J., and Qu, J., 2009, "Correction for partial reflection in ultrasonic attenuation measurements using contact transducers," *J. Acoust. Soc. Am.*, accepted for publication.

2. Cui, Z.W., Sun, Yi, and Qu, J., 2009, "The Neighbor List Algorithm for a Parallelepiped Box in Molecular Dynamics Simulations," *Chinese Science Bulletin*, vol. 54, pp. 1 - 7.
3. Dingreville, R. and Qu, J., 2008, "A Semi-Analytical Method to Estimate Interface Elastic Properties," *Computational Materials Science*, accepted for publication.
4. Pruell, C., Kim, J.Y., Qu, J., Jacobs, L.J., 2008, "Evaluation of fatigue damage using nonlinear guided waves," *Smart Materials and Structures*, accepted for publication.
5. Kuechler, S., Meurer, T., Jacobs, J. and Qu, J., 2009, "Two-Dimensional Wave Propagation in an Elastic Half-Space with Quadratic Nonlinearity -- A Numerical Study," *J. Acoust. Soc. Am.*, Vol. 125, 1290 - 1301.
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C. Other Publications

1. Jing, J., Gao, F. , Johnson, J., Liang, F.Z., Williams, R.L., Qu, J., 2008, "Simulation of Dynamic Fracture along Solder-Pad Interfaces Using a Cohesive Zone Model, Proceedings of IMECE 2008, ASME, IMECE, October 31-November 6, 2008, Boston, Massachusetts, USA, IMECE2008-68891.
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